Materials Declaration

Package	LFCSP
Body Size	10 X 10 X 0.85
LeadCount	72
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.9	1.43 E-01	510965
Epoxy & Phenol Resin	12.8	2.10 E-02	75137
Carbon black	0.3	5.09 E-04	1823
Subtotal		1.64 E-01	587925

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.62	9.76 E-02	349500
Fe	2.19	2.19 E-03	7846
Zn	0.11	1.13 E-04	405
P	0.07	7.30 E-05	261
Subtotal		1.00 E-01	358013

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	9.83 E-04	3520

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.18 E-03	11388

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.71 E-03	6131

Chip

	% of Chip	Weight (g)	PPM
Si	100	8.17 E-03	29268

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	73	7.70 E-04	2757
Epoxy Resin	18	1.92 E-04	688
Metal oxide	3	2.90 E-05	104
Curing and hardening agent	3	2.90 E-05	104
Gamma Butyrolactone	3	2.90 E-05	104
Subtotal		1.05 E-03	3756

Package Totals

Weight (g)	PPM
2.79 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	3	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.